

APPROVAL SHEET

WW12R, WW08R, WW06R

±1%, ±5%

Metal low ohm power chip resistors Size 1206 (1W), 0805 (0.5W), 0603 (0.33W) Sensing Type

*Contents in this sheet are subject to change without prior notice.



FEATURE

- 1. Metal ultra low and stable TCR performance
- 2. High power rating and compact size
- 3. High reliability and stability
- 4. Reduced size of final equipment
- 5. RoHS compliant & Lead free

APPLICATION

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- · Battery charger
- DC-DC power converter

DESCRIPTION

The resistors are constructed in a high grade low resistive metal body. The resistive layer is covered with a protective coat and printed a resistance marking code over it. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Lead free terminations.



Fig 1. Construction of Chip-R



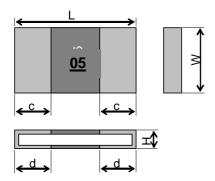
QUICK REFERENCE DATA

Item	General Specification			
Series No.	WW06R	WW08R	WW12R	
Size code	0603 (1608)	0805 (2012)	1206 (3216)	
Resistance Tolerance	±5% , ±1%			
Resistance Range	5, 10, 15mΩ	4, 5, 10mΩ,	1 ~ 15 mΩ	
TCR (ppm/°C)	±100 ppm/°C			
Max. power at T _{amb} =70°C	1/3 W	1/2 W	1W	
Max. Operation Current (DC or RMS)	8.1A, 5.7A, 4.7A	7A, 10A, 11.1A	31.6A ~ 8.2A	
Climatic category (IEC 60068)	55/155/56			

Note: Max. Operation Current: So called RCWC (Rated Continuous Working Current) is determined by

 $RCWC = \sqrt{Rated\,Power\,/Resistance\,Value}\ \ \text{listed above}.$

MECHANICAL DATA



Unit: mm

Туре	Size (inch)	Resistance	L (mm)	W (mm)	H (mm)	c (mm)	d (mm)
		5mΩ			0.33±0.10	0.20±0.10	0.50±0.10
WW06R	0603	10mΩ	1.60±0.10	0.80±0.10	0.30±0.10	0.20±0.10	0.30±0.10
		15mΩ	mΩ	0.22±0.10	0.20±0.10	0.20±0.10	
		4mΩ			0.30±0.10	0.30±0.10	0.65±0.10
WW08R	0805	5mΩ	2.0±0.15	1.25±0.15	0.30±0.10	0.30±0.10	0.58±0.20
		10mΩ			0.22±0.10	0.30±0.10	0.47±0.20
WW12R	1206	1mΩ	3.2±0.15	1.60±0.15	0.32±0.10	1.10:	±0.25
		2mΩ			0.32±0.10	0.50	±0.25
		3mΩ			0.35±0.10	0.70±0.25	1.30±0.25
		4mΩ			0.35±0.10	1.10:	±0.25
		5mΩ			0.35±0.10	1.00:	±0.25

6mΩ		0.35±0.1	0.80±0.25
7mΩ		0.35±0.1	0.70±0.25
8mΩ		0.35±0.1	0.50±0.25
9mΩ		0.28±0.1	0.55±0.25
10mΩ		0.28±0.1	0.50±0.25
11mΩ		0.22±0.1	0.80±0.25
12mΩ		0.22±0.1	0.70±0.25
13mΩ		0.22±0.1	0.60±0.25
14mΩ		0.22±0.1	0.55±0.25
15mΩ		0.22±0.1	0.50±0.25

MARKING

WW12R each resistor is marked with a 2-digit code with underline on the protective coating to designate the nominal resistance value. WW06R has no marking!

Example:

 $\frac{05}{10} = 0.005\Omega$ $\frac{10}{10} = 0.010\Omega$

FUNCTIONAL DESCRIPTION

Derating curve

The power that the resistor can dissipate depends on the operating temperature; see Fig.2

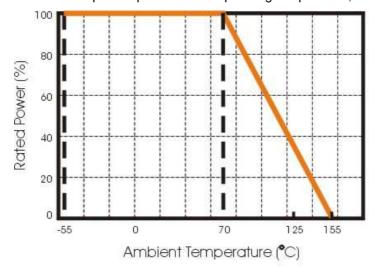


Fig.2 Maximum dissipation in percentage of rated power As a function of the ambient temperature



SOLDERING CONDITIONS

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 245°C during 3 seconds within lead-free solder bath. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig

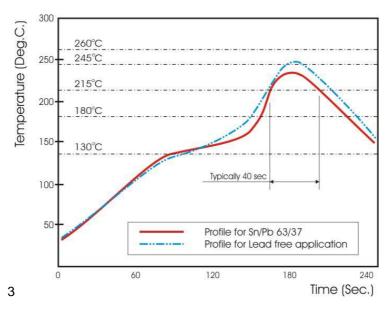


Fig 3. Infrared soldering profile for Chip Resistors WWxxR

CATALOGUE NUMBERS

The resistors have a catalogue number starting with .

WW06 R		R005	J	Т	L
Size code	Type code	Resistance code	Tolerance	Packaging code	Termination code
WW06 : 0603	R : 1/3W, 0603	R is first digit followed by 3	J : ±5%	T:7" reeled in tape	L = Sn base
WW08 : 0805	1/2W, 0805	significant digits.	F:±1%		(lead free)
WW12 :1206	1W, 1206	$0.010\Omega = R010$			
		$0.005\Omega = R005$			

Reeled tape packaging : 8mm width paper taping 5,000pcs per reel.



TEST & REQUIREMENTS

Table-4(1)

N.I.	T17	1able- 4(1)	D-f
No.	Test items	Condition of test (JIS C 5201–1)	Performance requirements
1	Visual examination	Sub-clause 4.4.1	As in 4.4.1
		Checked by visual examination.	The marking shall be legible, as
			checked by visual examination.
2	Dimension	Sub-clause 4.4.2	As specified in Table-3 of this
			specification.
	Resistance	Resistance value shall be measured by mounting	As in 4.5.2
		the substrate of the following condition.	The resistance value shall
		3	correspond with the rated resistance
		Current Current	taking into account the specified
		terminal terminal	tolerance.
		Copper dad Voltage terminal Solder resist	
		a: 2.9mm (2m Ω , 3mΩ, 4m Ω),	
		1.8mm (5m Ω)	
		Thickness of copper clad: 0.035mm	
		4-Terminal method	
		Measurement current: 1(A)	
		Note:The measuring apparatus corresponding to	
		DC Low-ohm Mater (1A) of AX-1152D for ADEX	
		CORPORATION.	
3	Voltage proof	Sub-clause 4.7	
		Method: 4.6.1.4(See Figure–5)	No breakdown or flash over
		Test voltage: Alternating voltage with a peak value	
		of 1.42 times the insulation voltage.	
		Duration: 60 s±5 s	
		Insulation resistance	
		Test voltage: Insulation voltage	R≥1GΩ
		Duration: 1 min.	
4	Solderability	Sub-clause 4.17	As in 4.17.4.5
		Without aging	The terminations shall be covered
		Flux: The resistors shall be immersed in a	with a smooth and bright solder
		non-activated soldering flux for 2 s.	coating.
		Bath temperature: 235 °C±5 °C	
-	B.C	Immersion time: 2 s±0.5 s	
5	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	Overload	Test substrate: Figure–3	
		Sub-clause 4.13	
	(in the mounted state)	The applied voltage shall be 2.5 times the rated	
		voltage or the current corresponding to.	
		Duration: 2 s Visual examination	No visible damage
		Resistance	ΔR≤±1%
	Solvent resistance of the	Sub-clause 4.30	Legible marking
	marking		Logico Harning
		Solvent: 2-propanol	
		Solvent temperature: 23 °C±5 °C Method 1	
		Rubbing material: cotton wool	
		Without recovery	
1	I	vvialout lectively	I



Table-4(2)

	Table=4(2)					
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements			
6	Mounting	Sub-clause 4.31				
		Substrate material: Epoxide woven glass				
		Test substrate: Figure-4				
	Bound strength of the end	Sub-clause 4.33				
	face plating	Bent value: 1 mm				
		Resistance	ΔR≤±1%			
	Final measurements	Sub-clause 4.33.6				
		Visual examination	No visible damage			
7	Resistance to soldering heat	Sub-clause 4.18				
		Solder temperature: 260 °C±5 °C				
		Immersion time: 10 s±0.5 s				
		Visual examination	As in 4.18.3.4			
			No sign of damage such as cracks.			
		Resistance	ΔR≤±1%			
	Component solvent	Sub-clause 4.29				
	resistance	Solvent: 2-propanol				
		Solvent temperature: 23 °C±5 °C				
		Method 2				
		Recovery: 48 h				
		Visual examination	No visible damage			
		Resistance	ΔR≤±1%			
8	Mounting	Sub-clause 4.31				
		Substrate material: Epoxide woven glass				
		Test substrate: Figure–3				
	Adhesion	Sub-clause 4.32				
		Force: 5 N				
		Duration: 10 s±1 s				
		Visual examination	No visible damage			
	Rapid change temperature	Sub-clause 4.19				
		Lower category temperature:-55 °C				
		Upper category temperature:+155 °C				
		Duration of exposure at each temperature: 30				
		min.				
		Number of cycles: 5 cycles.	No visible demons			
		Visual examination	No visible damage			
		Resistance	ΔR≤±1%			



Table-4(3)

No	Test items	Condition of test (JIS C 5201-1)	Performance requirements
9	Climatic sequence	Sub-clause 4.23	
	-Dry heat	Sub-clause 4.23.2	
		Test temperature: +155 °C	
	-Damp heat, cycle	Duration: 16 h Sub-clause 4.23.3	
	(12+12hour cycle)	Test method: 2	
	First cycle	Test temperature: 55 °C	
		[Severity(2)]	
	-Cold	Sub-clause 4.23.4	
		Test temperature –55 °C	
		Duration: 2h	
	-Damp heat, cycle	Sub-clause 4.23.6	
	(12+12hour cycle)	Test method: 2	
	Remaining cycle	Test temperature: 55 °C	
		[Severity (2)] Number of cycles: 5 cycles	
	-D.C. load	Sub-clause 4.23.7	
	D.O. load	The applied current shall be the rated current.	
		Duration: 1 min.	
		Visual examination	No visible damage
		Resistance	ΔR≤±5%
10	Mounting	Sub-clause 4.31	AK31570
	l	Substrate material: Epoxide woven glass	
		Test substrate: Figure-3	
	Endurance at 70 °C	Sub-clause 4.25.1	
		Ambient temperature: 70 °C±2 °C	
		Duration: 1000 h	
		The current shall be applied in cycles of 1.5 h on and 0.5 h.	
		The applied current shall be the rated current	
		Examination at 48 h, 500 h and	
		1000 h:	
		Visual examination	No visible demons
		Resistance	No visible damage ∆R≤±5%
			ΔR≥I3 /0



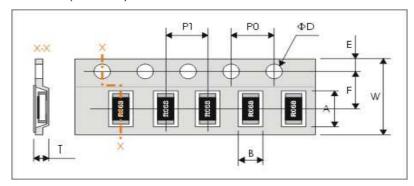
Table-4(4)

	Iable-4(4)						
No	Test items	Condition of test (JIS C 5201-1)	Performance requirements				
11	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3					
	Variation of resistance with temperature	Sub-clause 4.8 +20 °C / +155 °C	As in Table–1				
12	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3					
	Damp heat, steady state	Sub-clause 4.24 Ambient temperature: 40 °C±2 °C Relative humidity: 93 ½ % Without current applied. Visual examination	No visible damage Legible marking				
		Resistance	ΔR≤±5%				
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table–4				
	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3					
	Endurance at upper category temperature	Sub-clause 4.25.3 Ambient temperature:155 °C±2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination Resistance	No visible damage ΔR≤±5%				



PACKAGING

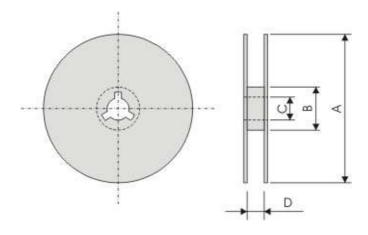
Paper Tape specifications (unit :mm)



Symbol	Α	В	W	F	E
WW06R	1.90±0.20	1.15±0.15			
WW08R	2.50±0.20	1.65±0.15	8.00±0.20	3.50±0.05	1.75±0.10
WW12R	3.60±0.20	2.00±0.15			

Symbol	P1	P0	ΦD	Т
WW06R				0.8 max.
WW08R	4.00±0.10	4.00±0.10	Φ 1.50 $^{+0.1}_{-0.0}$	1.0 max.
WW12R				1.0 max.

Reel dimensions



Symbol	Α	В	С	D
(unit : mm)	Ф180.0 -1.5	Φ60.0±1.0	13.0±0.2	9.0 +1.0

Taping quantity

- Chip resistors 5,000 pcs per reel.